

**Amendments To The Claims:**

1. (Cancelled).
2. (Previously Presented) The method of claim 17 wherein the through-hole is formed as a slot.
3. (Cancelled)
4. (Previously Presented) The method of claim 3 wherein the through-holes are formed as longitudinally oriented slots.
5. (Previously Presented) The method of claim 4 wherein the slots are arranged in a plurality of circumferentially spaced columns.
6. (Previously Presented) The method of claim 5 wherein the slots of circumferentially alternating columns of slots are staggered longitudinally.
7. (Previously Presented) The method of claim 5 wherein the mold cavity wall has at least three of said circumferentially spaced columns of slots.
8. (Previously Presented) The method of claim 7 wherein the mold cavity wall has four of said circumferentially spaced columns of slots.
9. (Previously Presented) The method of claim 17 wherein the at least one through-hole has a dimension at the mold cavity wall inner surface which does not allow substantial penetration of the parison material therethrough when heated to the temperature of the heated fluid and pressurized at a pressure sufficient to expand the parison to contact the mold cavity wall.
10. (Currently amended) The method of claim 17 wherein the at least one through-hole has a circular-an oval, diamond or square rectangular shape at the cavity wall inner surface.

11. (Previously Presented) The method of claim 17 wherein the mold cavity wall has a plurality of said through-holes arranged according to a pattern which extends circumferentially around the cavity wall.

12. (Previously Presented) The method of claim 17 wherein the mold cavity wall has a plurality of said through-holes arranged according to a pattern which extends helically around the cavity wall.

13. (Previously Presented) The method of claim 17 wherein the cavity has a portion having a diameter of at least 5 mm.

14. (Previously Presented) The method of claim 13 wherein said diameter is from about 8 mm to about 50 mm.

15-16. (Cancelled)

17. (Currently amended) A method of forming a medical device comprising the steps of placing a parison in a mold having a cavity with a wall form substantially conforming to the desired shape of said device, immersing the mold in a heated liquid fluid to heat the parison, and pressurizing the parison to radially expand the parison to contact the walls of the mold cavity, wherein the mold cavity wall contains at least one through-hole therein through which the heated liquid fluid enters the mold cavity to directly contact the parison when the mold is immersed in the heated fluid and through which heated liquid fluid that has entered the mold cavity is expelled therefrom when the parison is radially expanded, the at least one through-hole having a first dimension of at least about 0.1 mm and a second dimension of at least about 0.2 mm.

18. (Original) A method as in claim 17, further comprising agitating the heated fluid while the mold is immersed therein.
19. (Original) A method as in claim 17 further comprising vibrating the molding apparatus while the mold is immersed in the heated fluid.
20. (Original) A method as in claim 17 wherein the mold cavity wall contains a plurality of said through-holes therein.
21. (Cancelled)
22. (Previously Presented) The method of claim 17 wherein the heated liquid fluid is water, glycerol or an oil.
23. (New) A method of forming a medical device comprising the steps of placing a parison in a mold having a cavity with a wall form substantially conforming to the desired shape of said device, immersing the mold in a heated liquid fluid to heat the parison, and pressurizing the parison to radially expand the parison to contact the walls of the mold cavity, wherein the mold cavity wall contains at least one through-hole therein through which the heated liquid fluid enters the mold cavity to directly contact the parison when the mold is immersed in the heated fluid and through which heated liquid fluid that has entered the mold cavity is expelled therefrom when the parison is radially expanded, the at least one through-hole being substantially circular and having a diameter of at least about 0.1 mm.